Final Product Change Notification

202302029F01 : DSP56F807VF80(E) MAPBGA160 Qualification with AuPdCu Wire and G760L Mold Compound

Note: This notice is NXP Company Proprietary.

Issue Date: Mar 02, 2023 **Effective date:May 31, 2023**

Here is your personalized notification about a NXP general announcement.
For detailed information we invite you to view this notification online

Management summary

Addition of AuPdCu wire as a wire bond material along with Sumitomo G760L mold compound for the DSP56F807VF80/E devices.

Change Category

- [ ]Wafer Fab Process
- [ ]Wafer Fab Materials
- [ ]Wafer Fab Location
- [ ]Firmware
- [ ]Assembly Process
- [X]Assembly Materials
- [ ]Assembly Location
- [ ]Other
- [ ]Product Marking
- [ ]Mechanical Specification
- [ ]Packing/Shipping/Labeling
- [ ]Test Process
- [ ]Test Equipment
- [ ]Test Location
- [ ]Design
- [ ]Errata
- [ ]Electrical spec./Test coverage

PCN Overview

Description

NXP Semiconductors announces the addition of AuPdCu wire as a wire bond material along with Sumitomo G760L mold compound for the DSP56F807VF80/E devices associated with this notification.

This product is now qualified for assembly at ASE ChungLi (ASECL) assembly site, Taiwan. This product was previously assembled with CuPd wire and Sumitomo G760 mold compound at ASE ChungLi (ASECL) assembly site, Taiwan.

The AuPdCu wire and G760L Mold Compound conversion was successfully qualified adhering to NXP specifications.

Please see the attached file(s) for additional details.

Reason

Quality improvement.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information
Samples are available upon request
Production
Planned first shipmentJun 15, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
No Depletion of Inventory required.

Additional information

Self qualification:view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Apr 01, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.
About NXP Semiconductors
NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Orderable Part Number#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
DSP56F807VF80	935323918557	DSP56F807VF80	16BIT DSP	BGA160M	SOT1543-1	DOD	No	BLM1
DSP56F807VF80E	935323919557	DSP56F807VF80E	16 BIT HYBRID CONTROLLER	BGA160M	SOT1543-1	RFS	No	BLM1